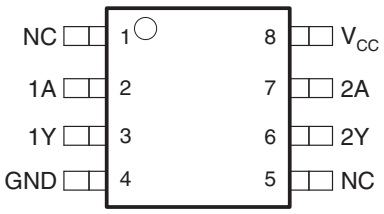
FEATURES

- **Wide Operating Voltage Range of 2 V to 6 V**
- **Outputs Can Drive up to 10 LSTTL Loads**
- **Low Power Consumption, 20-μA Max I_{CC}**
- **Typical t_{pd} = 7 ns**
- **±4-mA Output Drive at 5 V**
- **Low Input Current of 1 μA Max**
- **Unbuffered Outputs**

PS OR PW PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

The SN74HCU7204 contains two independent unbuffered inverters. The device performs the Boolean function $Y = \overline{A}$ in positive logic.

ORDERING INFORMATION

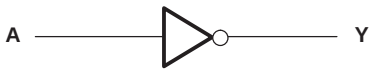
T_A	PACKAGE(1)		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SOP – PS		SN74HCU7204PS	HU7204
		Reel of 2000	SN74HCU7204PSR	
	TSSOP – PW	Tube of 90	SN74HCU7204PW	HU7204
		Reel of 2000	SN74HCU7204PWR	
		Reel of 250	SN74HCU7204PWT	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE
(EACH INVERTER)

INPUT A	OUTPUT Y
H	L
L	H

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		–0.5	7	V
I_{IK}	Input clamp current(2)	$V_I < 0$ or $V_I > V_{CC}$		±20	mA
I_{OK}	Output clamp current(2)	$V_O < 0$ or $V_O > V_{CC}$		±20	mA
I_O	Continuous output current	$V_O = 0$ to V_{CC}		±25	mA
	Continuous current through V_{CC} or GND			±50	mA
θ_{JA}	Package thermal impedance(3)	PS package		TBD	°C/W
		PW package		TBD	
T_{stg}	Storage temperature range		–65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
(3) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions(1)

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		2	5	6	V
V_{IH}	High-level input voltage	V_{CC} = 2 V	1.7			V
		V_{CC} = 4.5 V	3.6			
		V_{CC} = 6 V	4.8			
V_{IL}	Low-level input voltage	V_{CC} = 2 V			0.3	V
		V_{CC} = 4.5 V			0.8	
		V_{CC} = 6 V			1.1	
V_I	Input voltage		0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 4.5 V		–4		mA
		V_{CC} = 6 V		–5.2		
I_{OL}	Low-level output current	V_{CC} = 4.5 V		4		mA
		V_{CC} = 6 V		5.2		
t_t	Transition time	V_{CC} = 2 V	0		1000	ns
		V_{CC} = 4.5 V	0		500	
		V_{CC} = 6 V	0		400	
T_A	Operating free-air temperature		–40		85	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	T_A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
V_{OH}	V_I = V_{CC} or GND	I_{OH} = –20 µA	2 V	1.8			1.8		V
			4.5 V	4			4		
			6 V	5.5			5.5		
		I_{OH} = –4 mA	4.5 V	3.86			3.76		
		I_{OH} = –5.2 mA	6 V	5.36			5.26		
V_{OL}	V_I = V_{CC} or GND	I_{OL} = 20 µA	2 V			0.2		0.2	V
			4.5 V			0.5		0.5	
			6 V			0.5		0.5	
		I_{OL} = 4 mA	4.5 V			0.32		0.37	
		I_{OL} = 5.2 mA	6 V			0.32		0.37	
I_I	V_I = V_{CC} or 0		6 V			±100		±1000	nA
I_{CC}	V_I = V_{CC} or 0,	I_O = 0	6 V			2		20	µA
C_i			2 V to 6 V		3	10		10	pF

Switching Characteristics

over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

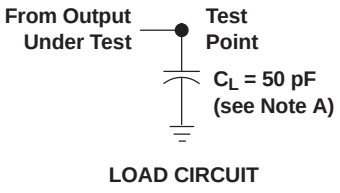
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
t_{pd}	A	Y	2 V		40	80		100	ns
			4.5 V		8	16		20	
			6 V		7	14		17	
t_r/t_f		Y	2 V		38	75		95	ns
			4.5 V		8	15		19	
			6 V		6	13		16	

Operating Characteristics

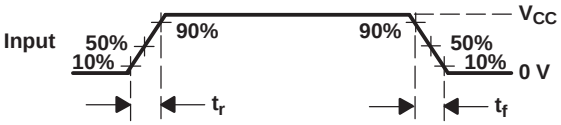
T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per inverter	No load	20	pF

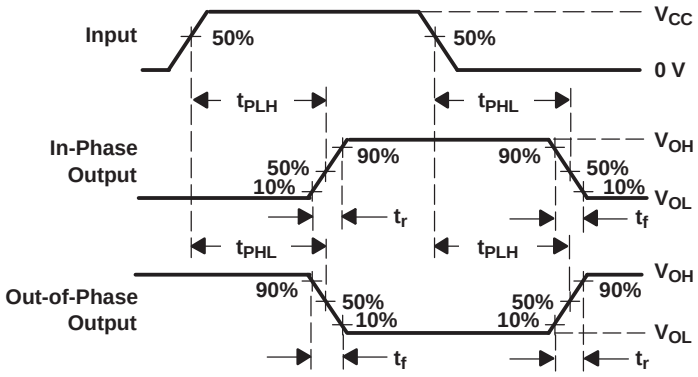
PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT



VOLTAGE WAVEFORM
INPUT RISE AND FALL TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

NOTES: A. C_L includes probe and test-fixture capacitance.
B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 6 ns, t_f = 6 ns.
C. The outputs are measured one at a time, with one input transition per measurement.
D. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74HCU7204PW	Active	Production	TSSOP (PW) | 8	150 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-	HU7204

(1) Status: For more details on status, see our product life cycle.

(2) Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

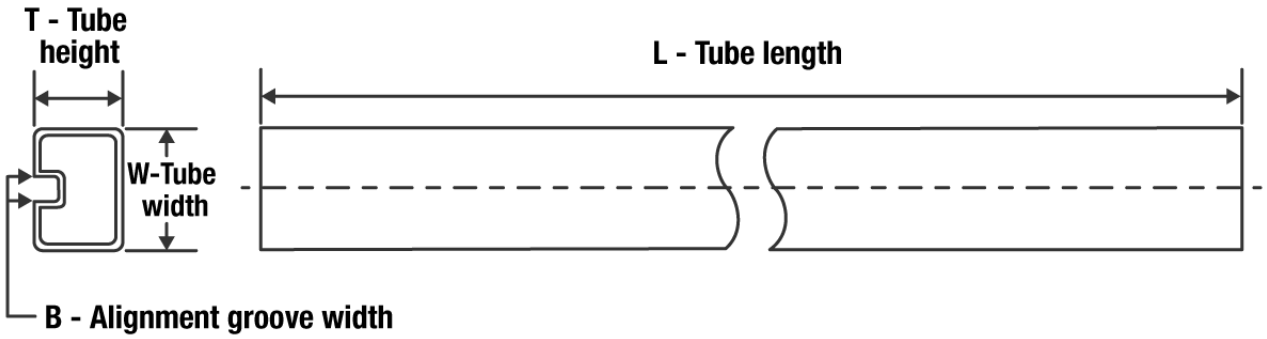
(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

TUBE



*All dimensions are nominal

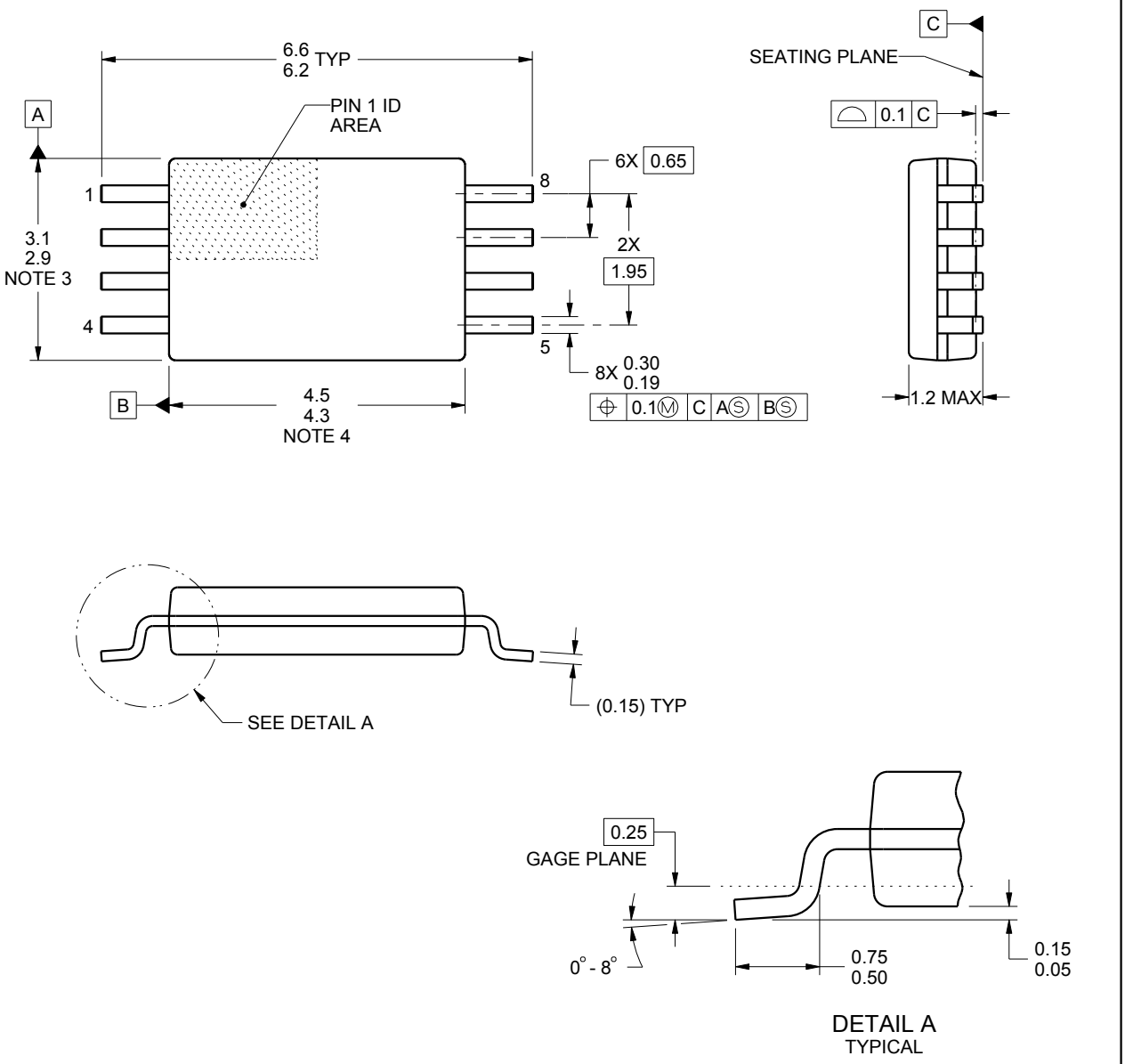
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74HCU7204PW	PW	TSSOP	8	150	530	10.2	3600	3.5

PACKAGE OUTLINE

PW0008A

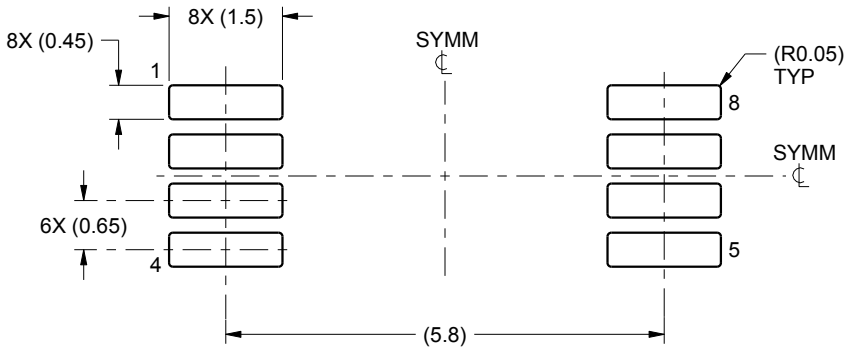
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

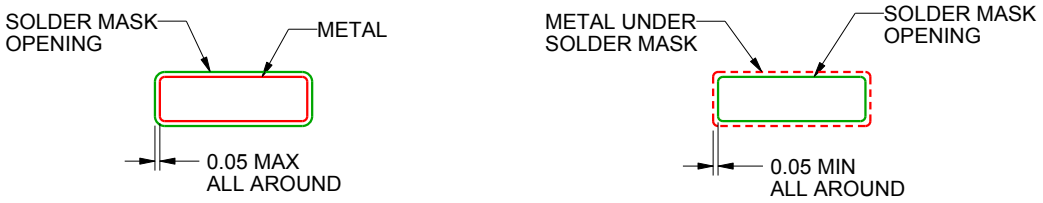


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153, variation AA.



LAND PATTERN EXAMPLE
SCALE:10X



SOLDER MASK DETAILS
NOT TO SCALE

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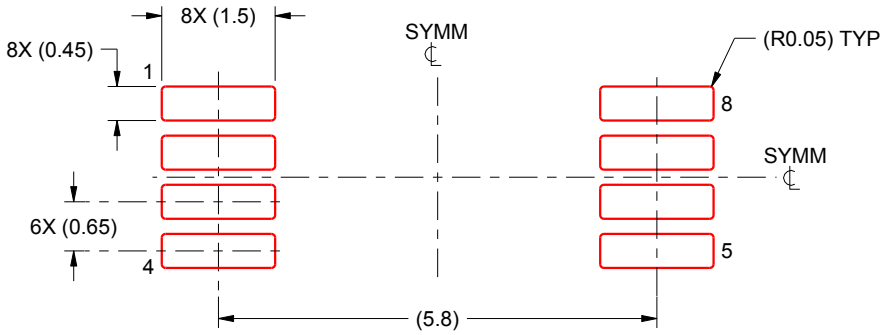
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:10X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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